

OSG60R099xSZF_Datasheet

Enhancement Mode N-Channel Power MOSFET

Features

- ◆ Ultra-fast and robust body diode
- ◆ Low $R_{DS(on)}$ & FOM
- ◆ Excellent low switching loss
- ◆ Excellent stability and uniformity
- ◆ Easy to drive

Applications

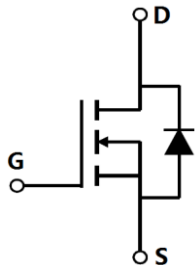
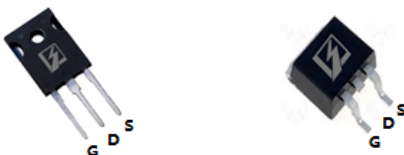
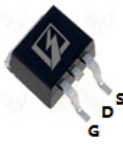
- ◆ PC power
- ◆ Server power supply
- ◆ Telecom
- ◆ Solar inverter
- ◆ Super charger for automobiles

■ General Description

OSG60R099xSZF use advanced GreenMOS™ technology to provide low $R_{DS(ON)}$, low gate charge, fast switching and excellent avalanche characteristics. This device offers extremely fast and robust body diode, and is suitable for telecom and super charger applications.

◆ $V_{DS, min@Tjmax}$	650 V
◆ $I_{D, pulse}$	108 A
◆ $R_{DS(ON), max @ V_{GS}=10 V}$	99 mΩ
◆ Q_g	66.8 nC

■ Schematic and Package Information

Schematic Diagram 	Pin Assignment-Top View  TO247 OSG60R099HSZF	 TO263 OSG60R099KSZF
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■ Absolute Maximum Ratings at $T_j=25^{\circ}\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	V_{DS}	600	V
Gate source voltage	V_{GS}	±30	V
Continuous drain current ¹⁾ , $T_C=25^{\circ}\text{C}$	I_D	36	A
Continuous drain current ¹⁾ , $T_C=100^{\circ}\text{C}$		22.8	
Pulsed drain current ²⁾ , $T_C=25^{\circ}\text{C}$	$I_{D, pulse}$	108	A
Power dissipation ³⁾ , $T_C=25^{\circ}\text{C}$	P_D	278	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	1000	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480$	dv/dt	100	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$, $I_{SD}\leq I_D$	dv/dt	50	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	°C

■ Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	0.45	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^{\circ}\text{C}/\text{W}$

■ Electrical Characteristics at $T_j=25^{\circ}\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	600			V	$V_{GS}=0\text{ V}, I_D=1\text{ mA}$
		650	740			$V_{GS}=0\text{ V}, I_D=1\text{ mA}$ $T_j=150^{\circ}\text{C}$
Gate threshold voltage	$V_{GS(th)}$	3.0		4.5	V	$V_{DS}=V_{GS}, I_D=1\text{ mA}$
Drain-source on-state resistance	$R_{DS(on)}$		0.082	0.099	Ω	$V_{GS}=10\text{ V}, I_D=18\text{ A}$
			0.20			$V_{GS}=10\text{ V}, I_D=18\text{ A},$ $T_j=150^{\circ}\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DSS}			10	μA	$V_{DS}=600\text{ V}, V_{GS}=0\text{ V}$
Gate resistance	R_G		8.0		Ω	$f=1\text{ MHz}, \text{Open drain}$

■ Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C_{iss}		4178		pF	$V_{GS}=0\text{ V},$ $V_{DS}=50\text{ V},$ $f=100\text{ kHz}$
Output capacitance	C_{oss}		202		pF	
Reverse transfer capacitance	C_{rss}		7.2		pF	
Turn-on delay time	$t_{d(on)}$		48.3		ns	$V_{GS}=10\text{ V},$ $V_{DS}=400\text{ V},$ $R_G=2\ \Omega,$ $I_D=20\text{ A}$
Rise time	t_r		77.0		ns	
Turn-off delay time	$t_{d(off)}$		90.9		ns	
Fall time	t_f		4.6		ns	

■ Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q_g		66.8		nC	$I_D=20\text{ A}$, $V_{DS}=400\text{ V}$, $V_{GS}=10\text{ V}$
Gate-source charge	Q_{gs}		16.6		nC	
Gate-drain charge	Q_{gd}		28.7		nC	
Gate plateau voltage	V_{plateau}		6.7		V	

■ Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward current	I_S			36	A	$V_{GS} < V_{th}$
Pulsed source current	I_{SP}			108		
Diode forward voltage	V_{SD}			1.4	V	$I_S=36\text{ A}$, $V_{GS}=0\text{ V}$
Reverse recovery time	t_{rr}		146.5		ns	$I_S=20\text{ A}$, $di/dt=100\text{ A}/\mu\text{s}$
Reverse recovery charge	Q_{rr}		1.0		μC	
Peak reverse recovery current	I_{rrm}		12.8		A	

■ Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_d is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of $R_{\theta JA}$ is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with $T_a=25\text{ }^\circ\text{C}$.
- 5) $V_{DD}=100\text{ V}$, $R_G=50\text{ }\Omega$, $L=60\text{ mH}$, starting $T_j=25\text{ }^\circ\text{C}$.

■ **Electrical Characteristics Diagrams**

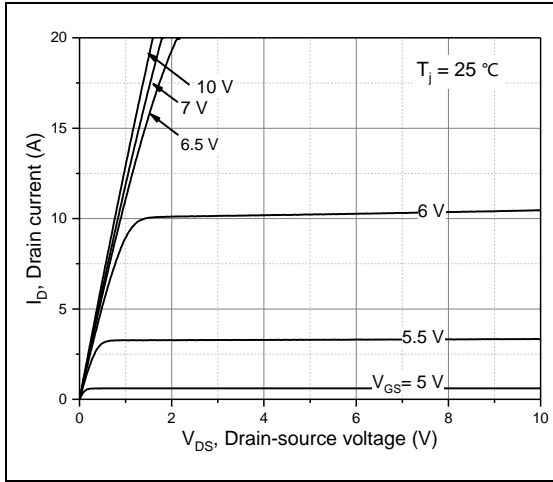


Figure 1, Typ. output characteristics

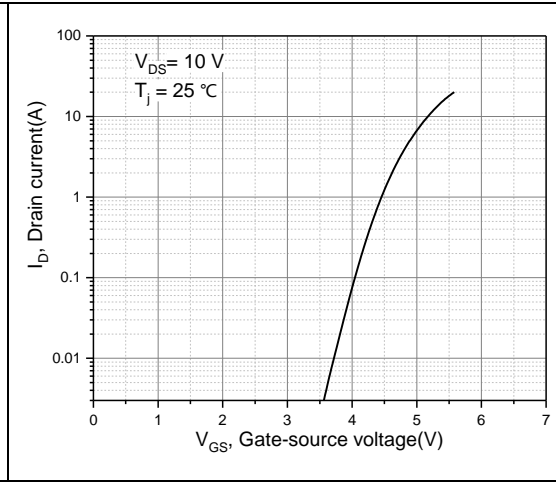


Figure 2, Typ. transfer characteristics

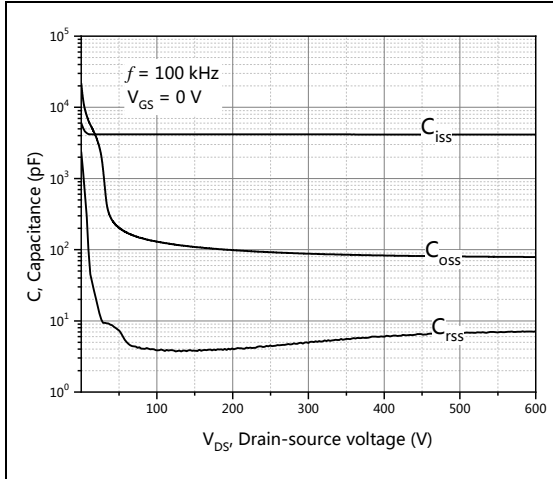


Figure 3, Typ. capacitances

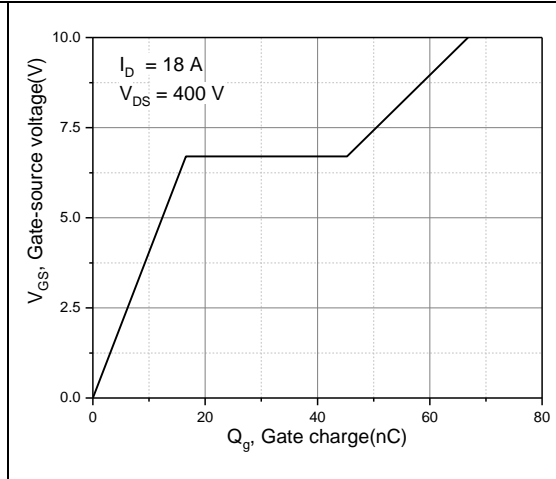


Figure 4, Typ. gate charge

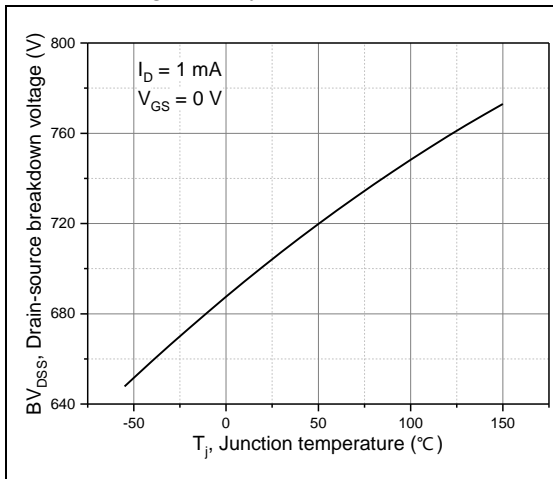


Figure 5, Drain-source breakdown voltage

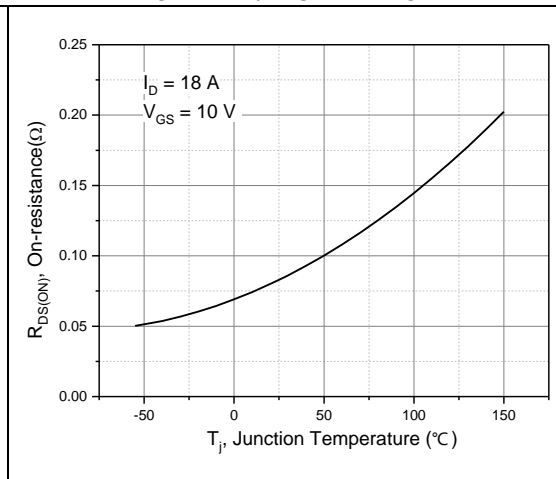


Figure 6, Drain-source on-state resistance

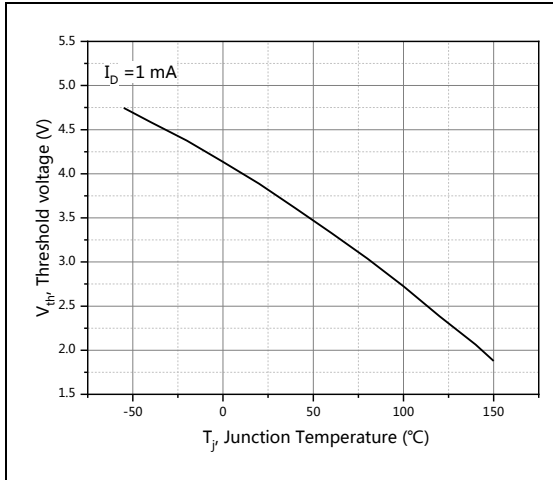


Figure 7, Threshold voltage

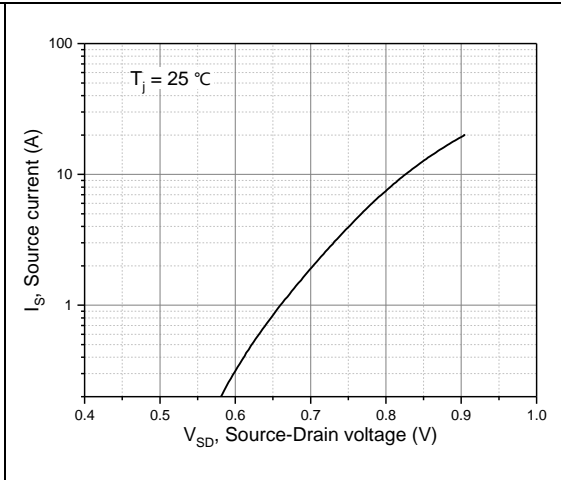


Figure 8, Forward characteristic of body diode

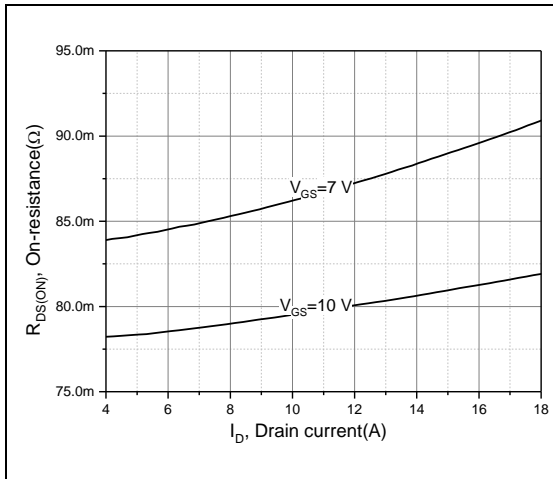


Figure 9, Drain-source on-state resistance

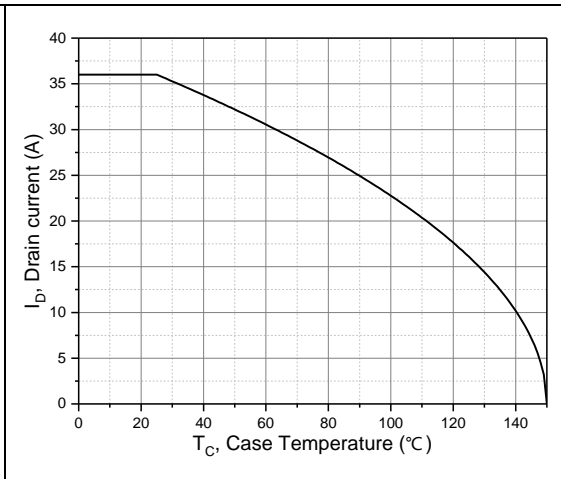


Figure 10, Drain current

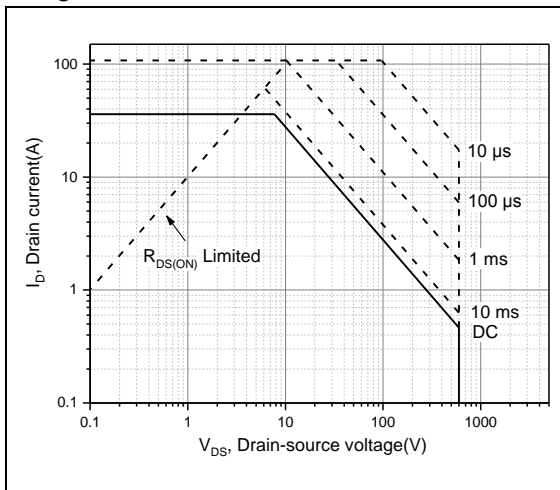


Figure 11, Safe operation area $T_C=25\text{ }^\circ\text{C}$

■ Test circuits and waveforms

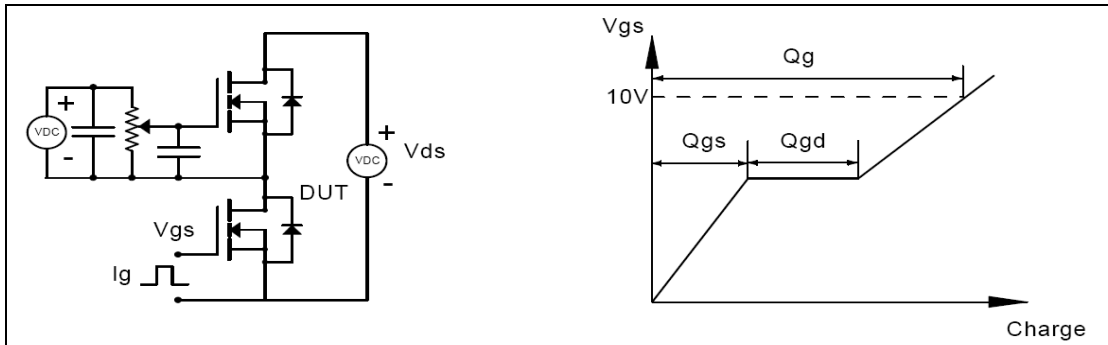


Figure 1, Gate charge test circuit & waveform

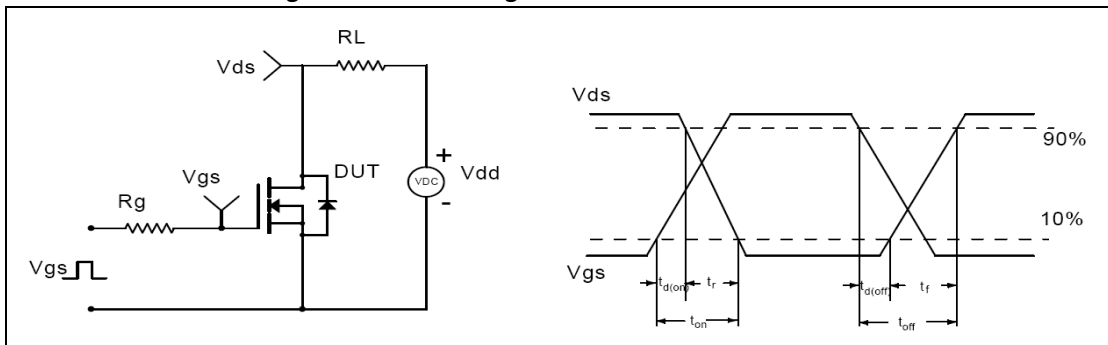


Figure 2, Switching time test circuit & waveforms

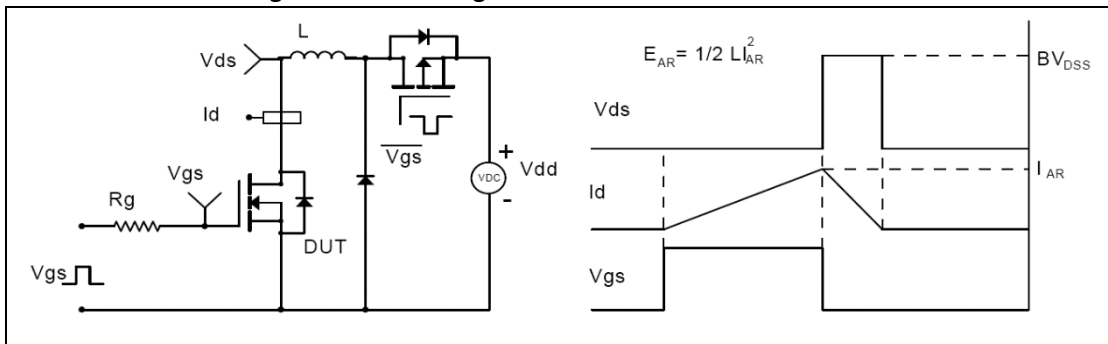


Figure 3, Unclamped inductive switching (UIS) test circuit & waveforms

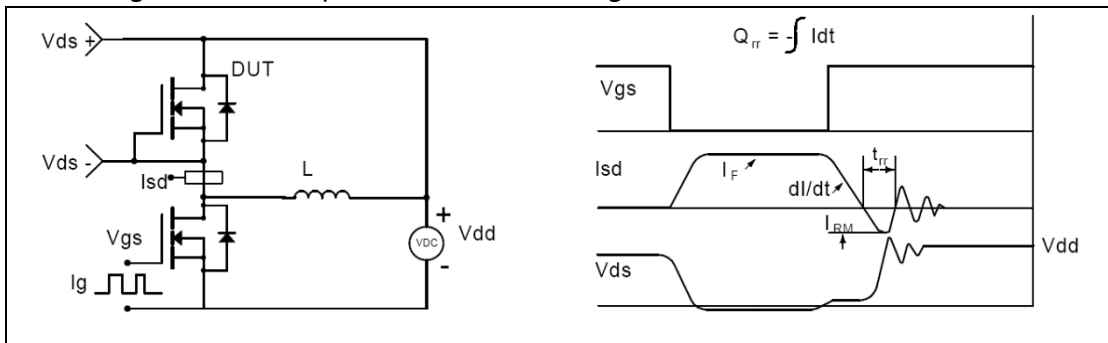


Figure 4, Diode reverse recovery test circuit & waveforms

■ Package Information

Figure1, TO247 package outline dimension

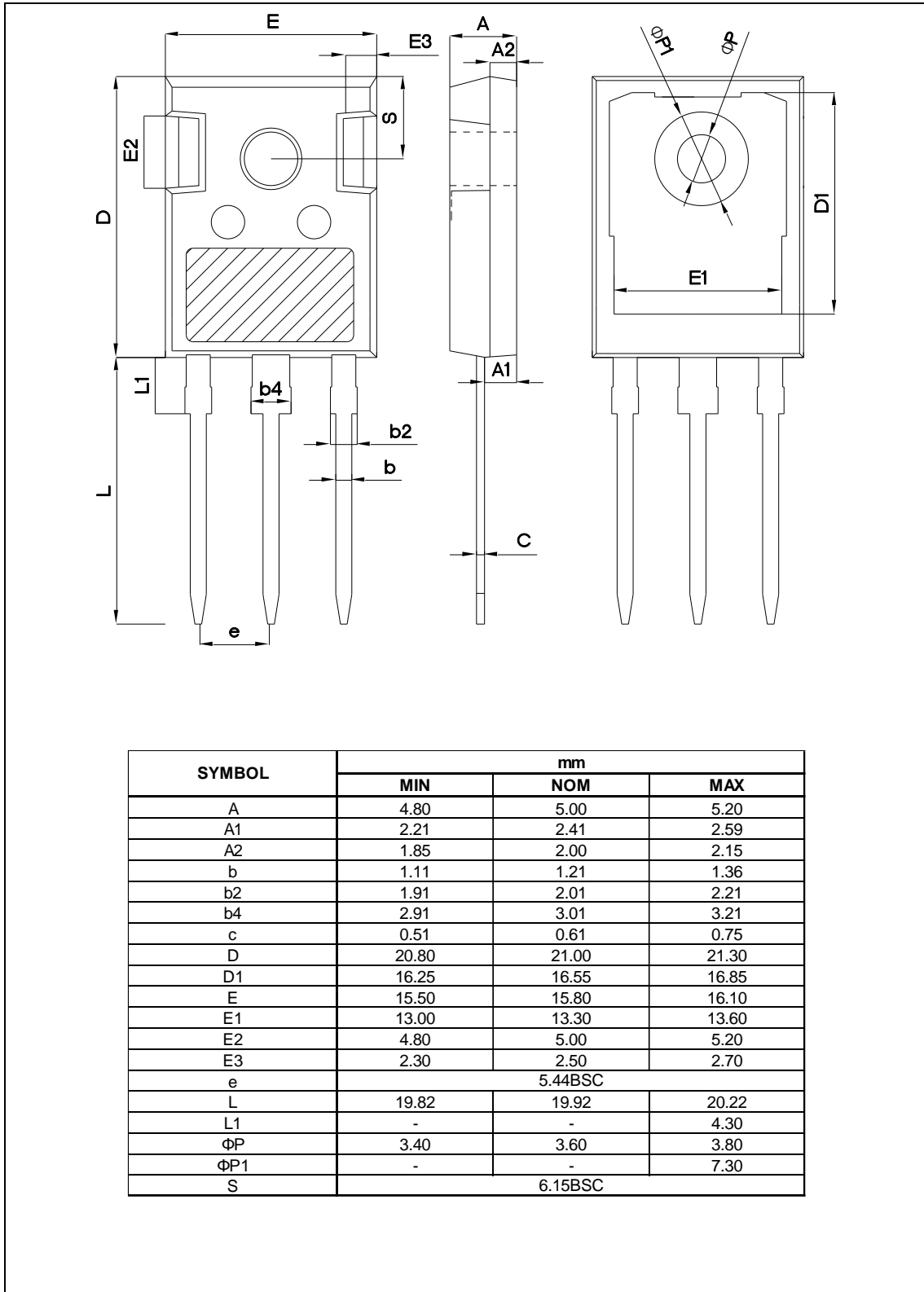
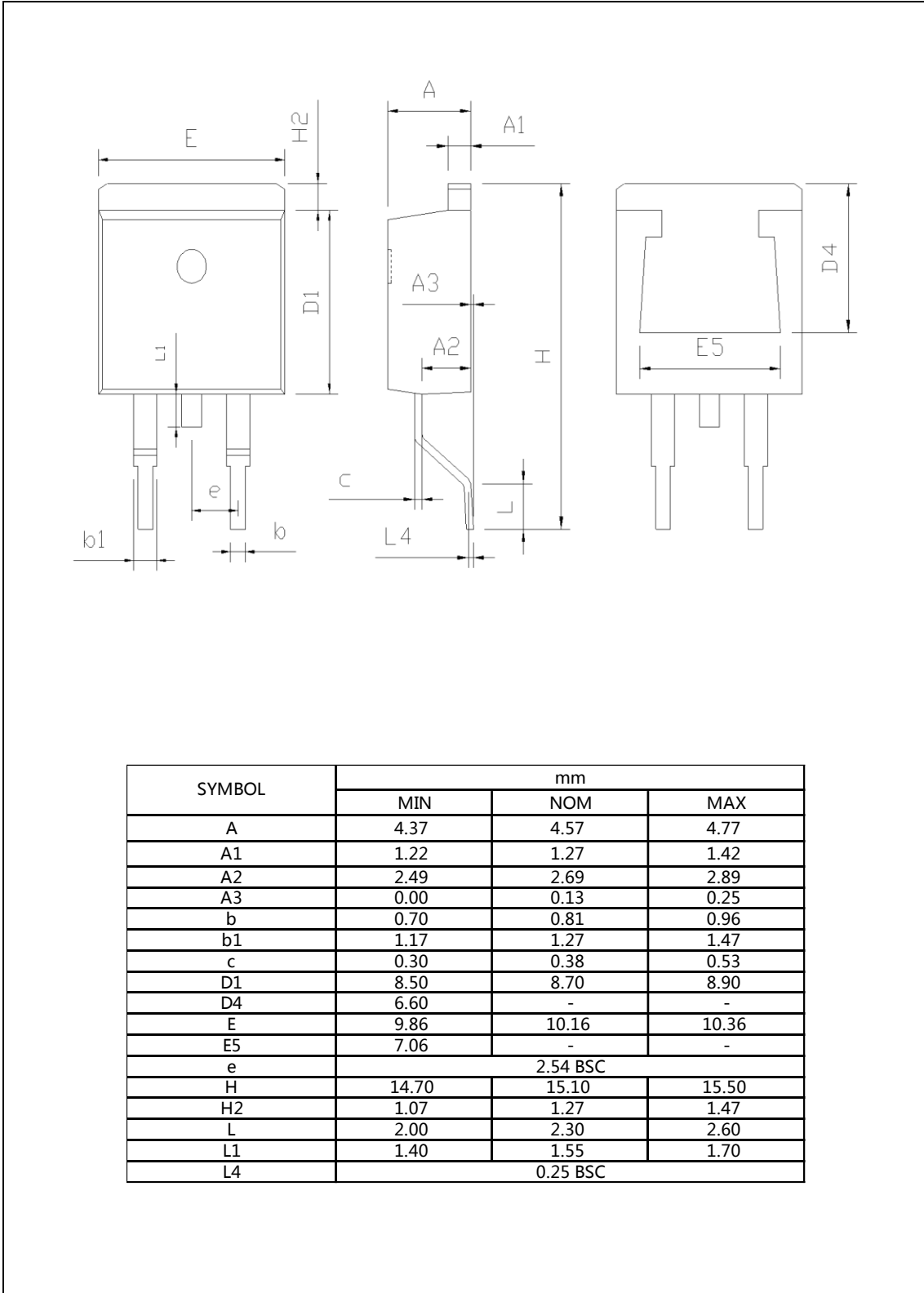


Figure2, TO263 package outline dimension



■ Ordering Information

Package	Units/Tube	Tubes/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO247	30	11	330	6	1980

Package	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Box/Carton Box	Units/Carton Box
TO263	800	1	800	10	8000

■ Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R099HSZF	TO247	yes	yes	yes
OSG60R099KSZF	TO263	yes	yes	yes